



The European Institute for the PCB Community

EIPC SPEeDNEWS

The Weekly On-Line Newsletter
Issue 33 – November 2023

NEWS FROM THE EIPC

Announcement **EIPC Winter Conference Germany** **January 30 & 31, 2024**

Reliability.

In a world where the organic version is less certain, and in an industry where this quality is essential, it is reassuring to know that another EIPC WINTER CONFERENCE is set to take place on 30th & 31st January next year. Past attendees to these will know of their comprehensive coverage of the matters pertinent to this industry, and their value in being fully informed commercially, economically and technically.

In sending out this CALL FOR PAPERS we trust that we may rely upon you for a contribution, within the many subject matters shown in the topics for discussion. That way we may arrange yet another Conference that our members habitually rely upon.

The conference will be held at the IHK Schwarzwald-Baar-Heuberg in Villing-Schwenningen. The headquarters hotel is the Holiday Inn Villingen-Schwenningen. We will visit Schweizer Electronic AG in Schramberg on January 30th in the afternoon.

We look forward to receiving your abstract before November 30th.
More details are available on www.eipc.org
Online conference registration is also available on www.eipc.org





The European Institute for the PCB Community

Call for papers

EIPC Winter Conference Germany 2024

January 30 & 31, 2024



Bonus Programme: Visit to Schweizer Electronic AG, Schramberg, DE

Presentations on the following topics can be included in the conference programme:

Keynote / Trends

- Business Outlook: Global and Regional Electronics Industry
- Business update and trends for 5G, Antenna and filter applications, and High Rel application
- Automotive, E-mobility, Energy, IoT, Medical Industrial Electronics, Aerospace, Avionics-G5
- Disruptive supply chain: Supply chain risk management
- Chips act

Environmental responsibility

- Sustainability development -Circular economy solutions through the whole supply chain- carbon footprint
- Green manufacturing; materials, processes

Roadmapping for 2024 and beyond

- Roadmap by market segments
- Technology Guidance through market needs
- Adapting processes, materials, chemistry, equipment to future technology needs
- Strategic Partnership and Planning for success through Networking

New Technologies: Success through Evolution- or Disruptive Technologies?

- Process and material technology development in Additive and Build-up Technologies
- Photonics: optical solutions in component and board level
- Packaging technologies, Chips Act
- Embedded technology: Passives, actives, RFID tags
- Nanotechnology and Printed electronics: 3D Electronics /conductive pattern/dielectric layers
- Material Technology- Laminate technologies - Coating technologies for
- New surface finishes
- New technology, Innovations and Invention

Equipment and process evolution to meet Technology and Quality and Reliability targets

- Equipment and process capabilities supporting controlled conductor design features for high frequencies
- Etching technology for improved conductor control and copper thickness tolerances
- Industry 4.0, Automation and AI in PCB manufacturing
- Imaging and Printing Technology
- Laser, Mechanical drilling
- ML-Pressing for high frequency product, improving variation
- Embedding components and Metal Core PCBs

Materials, Qualification, Reliability and Traceability requirements by Application

- Responsibility and Standards for Product Reliability and Safety
- In-house process control and Testing
- Material and finished product Testing and Safety

Test and Measurement methodology

- Copper: thickness and roughness -How to measure and verify copper roughness against new requirements
- Standardization and methodology
- Measurement automation – in production controls
- High frequency measurement and automaton
- Tools for Testing and ensuring product safety and reliability



Please visit
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NEWS FROM FINLAND

Aspocomp's Interim Report January-September 2023: Net sales fell short of the comparison period, operating profit turned negative in the third quarter

Aspocomp Group Plc, Interim Report, November 9, 2023, at 9:00 a.m. (EET)
THIRD QUARTER 2023 HIGHLIGHTS

- Net sales EUR 8.1 (10.4) million, decrease of 23%
- Operating result EUR -0.7 (1.4) million, -8.9% (13.1%) of net sales
- Earnings per share EUR -0.11 (0.20)
- Operative cash flow EUR 0.7 (1.8) million
- Orders received EUR 7.1 (9.5) million, decrease of 25%
- Equity ratio 66.4% (68.2%)

JANUARY-SEPTEMBER 2023 HIGHLIGHTS

- Net sales EUR 26.4 (29.0) million, decrease of 9%
- Operating result EUR 0.0 (3.8) million, 0.1% (13.0%) of net sales
- Earnings per share EUR -0.02 (0.54)
- Operative cash flow EUR 1.6 (3.4) million
- Orders received EUR 26.2 (32.1) million, decrease of 18%
- Order book at the end of the review period EUR 14.0 (19.6) million, decrease of 28%
- Equity ratio 66.4% (68.2%)

OUTLOOK FOR 2023

Inflation and interest rates, the risk of recession and the uncertainties posed by Russia's war of aggression will affect the operating environment of the company and its customers in the 2023 fiscal year. It is estimated that the recovery of the Semiconductor segment will be slower than expected, that investments will slow down in several of Aspocomp's customer segments, mainly due to the rise in interest rates, and that

inventory levels will remain high in different parts of the value chain until the end of 2023. The cycle of the Semiconductor Industry segment is expected to return to growth in the first half of 2024.

Aspocomp reiterates the guidance that was published on October 27, 2023. Aspocomp estimates that its net sales for 2023 will be clearly below the 2022 level and its operating result for 2023 is expected to remain negative. In 2022, net sales amounted to EUR 39.1 million and the operating result to EUR 4.5 million.

CEO'S REVIEW

"Aspocomp's third-quarter net sales were clearly below the comparison period and amounted to EUR 8.1 million. In addition to the prolongation of the slow phase of the semiconductor cycle, inventory levels are still high in various parts of our value chain. The willingness to invest is currently at a low level in several of our customer segments, mainly due to the rise in interest rates. Order intake amounted to EUR 7.1 (9.5) million and the order book at the end of the review period amounted to EUR 14.0 (19.6) million.

A temporary slowdown in the semiconductor cycle is typical for the industry. The slow phase of the cycle has been prolonged, and we estimate, based on common market data, that it will swing to growth in the first half of 2024. An upswing hinges on the recovery of demand in the ICT equipment market, such as phones and computers. The semiconductor industry's long-term growth prospects are still strong.

The weak market situation was strongly reflected in the net sales of both the Semiconductor Industry and Industrial Electronics customer segments. Also, in the Telecommunication and Automotive customer segments, net sales were lower than in the comparison period. In the Security, Defense and Aerospace customer segment, net sales growth continued, albeit at a slower rate than before.

Aspocomp's third-quarter operating result amounted to EUR -0.7 million. The decrease in net sales had a negative effect on the operating result. In addition, the planning work to increase production capacity in Oulu, which the company started earlier with the aim of ensuring future growth in line with its strategy, has been suspended for the time being due to the weakening of the demand situation. The possible continuation of the planning work will be decided on when it becomes evident that demand for printed circuit boards starts growing again. The planning work-related costs

totalled approximately EUR 0.5 million. These costs, which are not part of the usual business, were recorded in the third quarter's operating result. In order to adjust its production and costs to meet the temporarily reduced delivery volumes, Aspocomp held change negotiations with its personnel in the third quarter. As a result of the negotiations, the company plans to lay off 20-30 production employees at a time for a maximum of 90 days between September 2023 and February 2024.

Inflation and interest rates, the risk of recession and the uncertainties posed by the Russian war of aggression affect the operating environment of the company and its customers in the 2023 fiscal year. The cycle of the Semiconductor Industry segment is expected to return to growth in the first half of 2024. We reiterate the guidance that was published on October 27, 2023, and estimate that Aspocomp's net sales for 2023 will be clearly below the 2022 level and its operating result for 2023 is expected to remain negative. In 2022, net sales amounted to EUR 39.1 million and the operating result to EUR 4.5 million."



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NEWS FROM IBERIA

Cipsa Circuits has invested in a new InduBond Technologies SL Xpress 360x2 Induction heating lamination press

Spanish PCB manufacturer Cipsa Circuits has invested in a new InduBond Technologies SL Xpress 360x2 Induction heating lamination press. The new InduBond Xpress has successfully been implemented at the PCB manufacturer's production plant in Barcelona, Spain.

The InduBond X-Press 360 is described as a new way of laminating PCB, using Induction Heating Technology to deliver precisely the energy needed to cure the resins with no thermal delays in any direction of the stack. X, Y and Z direction. Cold Cycle is also done in the same chamber by forced air controlling air flow speed and water temp.

“The combination of simplicity of the process, flexibility to press any materials in any thickness we require, real time temperature measurement with close loop regulation control, the cleanliness of any mass-lam process and the excellent design and workmanship we found upon evaluating the Indubond Xpress,” says Nuria Vidal, General Manager at Cipsa Circuits, in a press release, “not to mention the excellent price/performance ratio and fast ROI, led us to make the decision for this system. in addition, this system It really uses a minimal space and the energy efficiency is very high.”

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NEWS FROM LITHUANIA

New PCB factory under construction in Vilnius.

Teltonika printed circuit board (PCB) factory is moving forward rapidly

Construction work on the site of the Teltonika printed circuit board (PCB) factory in Vilnius is moving forward rapidly. With the installation of reinforced concrete structures, the outline of the future plant has become clear, and on Tuesday, a symbolic time capsule with a letter to future generations was buried in the foundations of the building.

The 33,000 square metre factory will have the highest level of automation currently available and will employ around 250 highly skilled workers in the factory and administrative areas. The plant is expected to have its roof on later this year, followed by interior fitting-out work. The plant is expected to start operations in early 2025. It will be one of the most advanced plants of its kind in Europe and a unique project on the continent.

“It has been a couple of decades since anyone in Europe has built a new PCB factory. This market is dominated by Asian countries and Europe has a shrinking number of producers. Given these trends, the construction of this plant is of great importance for the further development of the Teltonika company group. This investment will allow us to shorten production lead times, expand intellectual property protection for the technologies we develop, reduce supply chain risks and become independent from third-party political decisions,” says Arvydas Paukštys, Founder and President of Teltonika company group.

A printed circuit board is the base of modern electronic devices on which various components, including semiconductor chips, are placed. Nowadays,

this element is hardly replaceable in the manufacturing of more complex electronics.

Teltonika is building a printed circuit board factory as part of a major project investment agreement signed with the Ministry of Economy and Innovation. The investment in the modern plant will amount to €143 million, most of which will be spent on the acquisition of special production equipment. Installation of the equipment is scheduled to start in the middle of next year.

Production processes will be fully digitalised to ensure short lead times and optimum production costs. The plant will specialise in the production of PCBs for high-tech products. It will develop technologies for HDI, SBU, and Flex-Rigid, as well as for the design of high-frequency PCBs.

Some of the mass production technology solutions will be used for the first time in Europe. For example, it will be the first plant on the continent to use only digital solder mask printing technology and Vertical Continuous Plating (VCP) for mass production. There will also be a strong focus on ecology, with wastewater and process water from production being treated and recycled back into production, thus minimising and treating the wastewater generated.

Teltonika is supported in this ambitious project by Rico Schluter, who has extensive experience in this market. He has been working in the PCB industry for more than 4 decades and has helped customers build several such plants during his career.

“After working 41 years in the PCB-industry, personally, I am very proud to be a part of this unique project that will give a significant boost to the European PCB industry and its supply chain. Cooperation with the Teltonika project team is an absolute pleasure and I am very happy that I can share my very long experience in the PCB industry with my Lithuanian project - team members,” says Mr Schluter.

The PCB plant is one of the projects of the Teltonika High-Tech Hill Technology Park being developed in Liepkalnis, Vilnius. Ten new industrial and administrative buildings will be built in several phases over five years, and around 6,000 employees are expected to be employed.

In addition to the PCB factory, new electronic assembly and plastic injection moulding plants, a data centre, offices, laboratories and a

commercial building will be built on the 50 hectares of Teltonika High-Tech Hill. A semiconductor chip assembly, testing and manufacturing complex will be a key part of this technology park. The total investment in the Teltonika High-Tech Hill Technology Park over the next decade will be around €3.7 billion.



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NEWS FROM THE CHANNEL ISLANDS

Offshore Electronics has invested more than £400,000 into its manufacturing headquarters in St Peter Port, Guernsey

Offshore Electronics has invested more than £400,000 into its manufacturing headquarters in St Peter Port, Guernsey. Both production machinery and in-house communications have been upgraded to support the record levels of growth experienced by the business over the past year.

Offshore's turnover hit £10m for 2022/2023, with both new and existing customers signing multi-year agreements. As is now standard for the Guernsey-based contract electronics manufacturer (CEM), the proceeds of this success are being redirected back into the business to support its long-term growth and move into new markets.

The investment will expand Offshore's PCB production capabilities, increase productivity and connect employees working across its 20,000 sq. ft facility. Among the most important additions is a new axial component inserter from Southern Machinery, which will allow the business to position more than 20,000 axial parts per hour.

This is a key upgrade as many customers have designs that rely heavily on this type of component. Offshore's willingness to invest in this area guarantees a future for legacy products that would be cost-prohibitive to redesign for use with newer components.

New Inspex HD digital inspection cameras have been added to Offshore's QA and surface mount departments. These cameras are important for quality control but also assist employees as components become smaller and more difficult to examine. Some parts now measure as little as 0.5mm

x 0.2mm, making it impossible for the human eye to inspect adequately without magnification.

Offshore has also invested in the new Novastar Gold Wave soldering system, which will allow staff to rework or repair boards more efficiently. In addition to the Novastar is a new Heller surface mount oven and DEK screen printer, both replacing older models. Offshore has also installed CAT6 cabling, a new server, phone system and high-speed network connectivity for secure contact with clients across the world.

This latest outlay extends a pattern of investment, with the company having already purchased several other machines over the last 12 months. This includes a cutting-edge Yamaha Z:LEX YSM20R modular pick and place machine. The business has also made a significant commitment to sustainable PCB production, having recently signed off a major solar PV installation, due to be installed on the factory's roof in 2024. This will provide roughly 11% of the company's annual energy.

Paul van der Tang, Purchasing Director said: "Sustained investment in both people and technology is critical for maintaining a high standard of PCB production. This is a strategy we have adopted since starting in 1990 and it has continued to pay dividends, keeping us competitive in a crowded market. The latest round of capital is about cementing our position as a leading provider of electronics manufacturing services – both in Europe and beyond. It's a signal of intent as we develop relationships with both long-standing customers and those new to our business."



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NEWS FROM THE NETHERLANDS

Adeon Technologies received multiple purchase orders from Teltonika to supply the company with numerous types of equipment to their new PCB manufacturing plant in Vilnius, Lithuania

EIPC member Adeon Technologies, a Dutch distributor of equipment for the European PCB industry, has received multiple purchase orders from Teltonika to supply the company with numerous types of equipment to their new PCB manufacturing plant in Vilnius, Lithuania.

In a press release, Adeon explains that the initial conversation between the companies started in early 2022 and revolved around offering solutions and providing plans for installation training and long-term support.

Teltonika's new PCB plant will be the first new volume PCB factory to be built in Europe in more than 20 years. And according to Adeon who will supply a big chunk of the equipment, the factory will see an extremely high level of automation.

"Adeon Technologies is truly proud of having been involved from an early stage and extremely honoured to have been selected as one of the leading supply partners in the project," the Dutch company writes in the press release, adding that "Teltonika's new PCB factory marks a true milestone for making steps to secure crucial PCB manufacturing in Europe."

Installation of the ordered machines is expected to take place in due course during 2024, and Adeon has already assigned a project team to ensure a smooth delivery and implementation of the equipment. And looking at the order - It's a long shopping list for the future plant.



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NEWS FROM THE UK

Ventec Giga Solutions to distribute Cardel Specialist PCB Lamination Materials

Ventec Giga Solutions, the equipment division of Ventec International Group has been appointed as sales agent and distributor of specialist PCB lamination materials from Cardel. The agreement covers the EMEA region including the United Kingdom.

With state-of-the-art manufacturing sites in the United Kingdom and Germany, Cardel is a world leader in the manufacture of lamination plates and lamination pads for a wide range of PCB manufacturing applications. The materials are designed to provide consistently high quality, durability and performance in many industrial applications offering customers genuine value in their operations.

Cardel plates are produced with different hardness levels and materials, and the lamination pads are available in a wide range of materials and composite layered formats utilizing aramid, butyl rubber, silicone, brass, and copper.

“Partnering with Cardel is a great opportunity for Ventec Giga Solutions to offer our customers high-quality PCB lamination materials from a global leader,” said Ramesh Dhokia, Business Unit Director, Ventec Giga Solutions. “We are excited to showcase our new relationship with Cardel at Productronica 2023 at booth B3/242 from 14th to 17th November in Munich.”

Mark Goodwin, COO of Ventec International Group added: “The agreement with Cardel further strengthens our one-stop-shop solution of distributed

PCB manufacturing equipment, consumables and materials for PCB manufacturing customers, OEMs and EMS in the EMEA, UK and Americas regions.”

Ventec Giga Solutions handles factory design, equipment selection, sales, installation, commissioning, and training on behalf of customers. The division’s competencies and connections with numerous leading equipment suppliers, combined with the Ventec portfolio of high-performance substrate laminates and prepregs, presents a one-stop-shop for PCB manufacturers, OEMs, and manufacturing services companies to quickly establish and rapidly expand their facilities

eXception PCB, based In Tewkesbury, UK, installed the first Taiyo Circuit Automation DP3500 coater into the UK

Taiyo Circuit Automation is proud to have partnered with eXception PCB, a leading printed circuit board manufacturer based in Tewkesbury, Gloucestershire, UK to install the first Taiyo Circuit Automation DP3500 coater into the UK.

The DP3500 coater is a semi-automatic double-sided screen printer. The DP3500 comes with the new Smart Print System which delivers superb quality with minimal panel thickness of 1 mil combined with a toolless magnetic gripper system that tensions the panel as it prints. Additionally, the new HMI Touch Screen, Differential Print Pressure Control System and Servo Controlled Peel Off features now come as standard. eXception’s new DP3500 is combined with Taiyo America’s PSR-4000, the global leading solder mask system, to complete the “Taiyo Zone” print room at eXception.

“eXception has been a long-standing partner of Taiyo Circuit Automation, having had a DP2500 for many years. This new coater will support eXception’s continued growth into new technology sectors. The DP3500, with its new multi programmable settings for panel type, size and thickness, and with extraordinary print quality, when combined with Taiyo’s PSR-4000 solder mask is a winning combination as demonstrated by thousands of customers worldwide.

Taiyo, as the largest supplier of solder mask in the world, can now leverage the global recognition of Taiyo Circuits Automation’s coaters and ovens. This is the perfect solution for PCB manufacturers,” said Stuart Down, EMEA Sales Manager for Taiyo Europe.

“The entire installation process went very well with very little down time as we transitioned from the old coater to the new DP3500. Taiyo Circuit

Automation's engineers were on site with support from Viking Test agents based in the UK provided outstanding support during the transition," said Kamal Berberi, Director of Operations for eXception PCB. "Our throughput has doubled through the department with this new coater, the solder mask tolerances across the panel have greatly improved due to the smart print system, and we are now looking ahead to working with Taiyo on their new PSR-4000 HH01XR DI melamine free system to address some of the new regulations coming out of ECHA and REACH," said Jamie Ashton, Head of department for eXception PCB.

Taiyo Circuit Automation, Inc. was established as a subsidiary of Taiyo America, Inc in 2020, in Carson City, NV. We design and manufacture the world's finest dual-sided solder mask coating and vertical drying equipment. We have served the printed circuit industry with highly reliable innovative machinery, engineered to exceed expectations.

eXception PCB, established in 1977 and founded in Cheltenham, Gloucestershire. We are a European time critical, and technology driven printed circuit board manufacturer. Specializing in quick-turn, low to medium volume, standard multi-layer, flex, flex-rigid and High-Density Interconnection (HDI) solutions for a wide range of industries including aerospace, medical, telecommunications, defence and automotive.

Ventec Giga Solutions, the equipment division of Ventec International Group announces it has been appointment by Surge Robotic as sales agent and distributor of Optical PCB Layup Systems

Ventec Giga Solutions, the equipment division of Ventec International Group announces it has been appointment by Surge Robotic as sales agent and distributor of Optical PCB Layup Systems. The agreement covers EMEA, UK and the Americas.

Surge Robotic was founded in 2020 and launched the industry's first four-camera optical PCB laminating system after two years of extensive research and development. The Falcon Lineup offers unprecedented precision and productivity.

Falcon employs four corner etch targets to align and detect PCB inner layer deformation to calculate and modify placement. Scratch free handling for all PCB layers of any type of material is ensured. Additionally, PCB manufacturers can use inner layer measurement data to monitor and adjust their processes accordingly, thus enabling Smart Manufacturing.

“Falcon offers the fastest layup system on the market and is optionally available with a fully automatic loading system,” said Ramesh Dhokia, Business Unit Director, Ventec Giga Solutions. “With our goal to provide our customers with the best PCB manufacturing equipment available in the industry, we are thrilled to add them to our Ventec Giga Solutions offering. We are excited to showcase our new relationship with Surge Robotic at Productronica 2023 at booth B3/242.”

“We aim to leverage Surge Robotics’ breakthrough technology and innovative spirit into a competitive advantage within our Ventec Giga Solutions PCB equipment lineup. Their unique machine technology delivers the value and performance our customers need for the future of manufacturing,” added Mark Goodwin, COO of Ventec International Group.

Yeitek Appoints Ventec Giga Solutions as Distributor for PCB Cleaning Equipment

Ventec Giga Solutions, the equipment division of Ventec International Group, announces that it has been appointed as sales agent and distributor of Taiwanese manufacturer Yeitek's specialized PCB cleaning machines and accessories. The agreement encompasses EMEA, the United Kingdom, and the Americas.

Yeitek cleaning machines and accessories are made to effectively address and prevent FOD contamination to ensure defect-free, cost-efficient PCB production processes. The range of equipment offers single- and double-sided automated cleaning choices that utilise specially formulated adhesive rolls and absorbing rollers to efficiently remove any dust and/or debris.

“This is the beginning of a significant partnership, and I am very excited to be working with Yeitek as we develop our capabilities and equipment offering through Ventec Giga Solutions to deliver a consistently excellent customer experience to current and new customers,” said Ramesh Dhokia, Business Unit Director, Ventec Giga Solutions. “We are thrilled to present our new partnership with Yeitek at Productronica 2023 on **Booth B3/242**, which will take place in Munich from 14th – 17th November.”

Mark Goodwin, COO of Ventec International Group added: “The appointment represents a great opportunity for Ventec to expand and support Yeitek’s customer base, whilst at the same time strengthening our one-stop-shop solution for PCB manufacturers, OEMs, and EMS. Yeitek has

served customers in the PCB industry for nearly 40years, and we are proud to have such an important partnership.”

Further information about Ventec’s solutions and the company’s wide variety of products is available at www.venteclaminates.com.

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NEWS FROM THE TPCA

Compeq rises out of 1H23 slump to new 4Q highs

Major High-Density Interconnect (HDI) board manufacturer Compeq announced its latest financial report during its board meeting on November 9. For the third quarter of 2023, the company's revenue reached NT\$19.59 billion (US\$ 605 million), a quarterly increase of 41.3%; gross profit margin was 15.88%, a quarterly increase of 3.54 percentage points; and net income after tax was NT\$1.68 billion (US\$51.9 million), a quarterly increase of 180%.

Compeq has expressed relief in finally coming out of the slump that marked the first half of 2023. Industry observers share the company's optimism, as Compeq is both one of the major HDI board suppliers for US smartphone brands and a high-end HDI board supplier for smartphone brands in China. As Chinese brands renew their efforts in launching high-end smartphones, Compeq is expected to benefit as well.

Through the first half of 2023, Compeq digested inventory as consumer demand remained weak. As its clients began shipping new products in the third quarter, the company saw revenue climb steadily beginning in July. Revenue in October reached NT\$7.319 billion (US\$226 million), marking the third-highest monthly revenue in company history, and these high figures are expected to continue into the fourth quarter with the traditional year-end consumer electronics sales promotions.

In addition to supplying US brands with smartphone mainboards, rigid-flex PCBs for periscope lenses, and flexible PCBs for batteries, Compeq is also one of the main suppliers of M3-powered notebooks. With its Chinese-brand smartphone clients also launching new products to rave reviews, these will no doubt boost the company's bottom line in the fourth quarter. Moreover, Compeq stands to benefit from its US clients' offering direct-to-cell services via Starlink since the company is the sole supplier of satellite boards. With a second US client successfully launching its second low Earth

orbit (LEO) satellite in October, Compeq's long-term partnership with LEO satellite companies continues to bear fruit, as these satellites are understood to use Compeq-manufactured PCBs as well.

Looking ahead, Compeq has seen progress in courting server and network communications clients and is branching into AI products and co-packaged optics (CPO) boards for use in network communications. Smartphone industry experts note that, as smartphones gain satellite communications and AI functions, the challenge lies in how to incorporate an increasing number of components inside a limited space while also maintaining battery life.

Compeq expects capital expenditure for 2023 to hold at roughly NT\$7 billion (US\$216 million), with main expenditures including equipment for modified semi-additive process (mSAP) HDI, flexible, and surface mount technology (SMT) boards, and the construction of production facilities in Thailand. The company's new Thailand factory broke ground in June 2023 and once construction is completed, the firm will focus on rigid boards for satellite communications, servers, and automotive applications. Production is slated to begin in 2024, with room for adjustment based on clients' demands.



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International Diary

2023

23rd EIPC Technical Snapshot Webinar

Registrations via www.eipc.org

December

2024

EIPC Winter Conference

Visit Schweizer Electronic AG

Schramberg/Villingen-Schwenningen, Germany

Tuesday 30 & Wednesday 31 January

EIPC @ ECWC16 WECC

Anaheim, USA

April 8-11

EIPC Summer Conference

Visit ESTEC

Noordwijk, The Netherlands

Tuesday 4 & Wednesday 5 June